

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WANG-LAI YANG	03/03/2011
RECEIVING PARTY DATA	
Name:	Ambit Microsystems (Zhongshan) LTD.
Street Address:	Ambit Microsystems (Zhongshan) LTD.,Zhongshan Torch Hi-tech Development Zone
City:	Zhongshan City, Guangdong Province
State/Country:	CHINA
Name:	HON HAI PRECISION INDUSTRY CO., LTD.
Street Address:	66,CHUNG SHAN ROAD
City:	Tu-Cheng, New Taipei
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13069390
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	Raymond J. Chew
Total Attachments: 2 source=US34050110321ASM#page1.tif source=US34050110321ASM#page2.tif	

CH \$40.00 13069390

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1. WANG-LAI YANG , residing at Zhongshan, Guangdong, China
2. _____ , residing at _____
3. _____ , residing at _____
4. _____ , residing at _____
5. _____ , residing at _____
6. _____ , residing at _____
7. _____ , residing at _____
8. _____ , residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **AMBIT MICROSYSTEMS (ZHONGSHAN) LTD.** having a principal place of business at **Zhongshan Torch Hi-tech Development Zone Zhongshan City, Guangdong Province, P.R.C.** and **HON HAI PRECISION INDUSTRY CO., LTD.** having a principal place of business at **66, Chung Shan Road, Tu-Cheng Dist., New Taipei City, Taiwan, R.O.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **LEAD FRAME, METHOD OF MANUFACTURING THE SAME, AND SEMICONDUCTOR PACKAGE USING THE SAME** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____

[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>Wang-Lai Yang</u> WANG-LAI YANG	<u>Mar.03,2011</u> Date
2.	_____	_____ Date
3.	_____	_____ Date
4.	_____	_____ Date
5.	_____	_____ Date
6.	_____	_____ Date
7.	_____	_____ Date
8.	_____	_____ Date
9.	_____	_____ Date